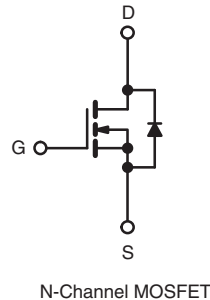
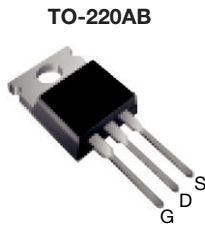


E Series Power MOSFET with Fast Body Diode

| PRODUCT SUMMARY | |
|---|-------------------------|
| V_{DS} (V) at T_J max. | 700 |
| $R_{DS(on)}$ max. at 25 °C (Ω) | $V_{GS} = 10$ V 0.156 |
| Q_g max. (nC) | 122 |
| Q_{gs} (nC) | 17 |
| Q_{gd} (nC) | 36 |
| Configuration | Single |



FEATURES

- Fast Body Diode MOSFET using E Series Technology
- Reduced t_{rr} , Q_{rr} , and I_{RRM}
- Low Figure-of-Merit (FOM) $R_{on} \times Q_g$
- Low Input Capacitance (C_{iss})
- Low Switching Losses Due to Reduced Q_{rr}
- Ultra Low Gate Charge (Q_g)
- Avalanche Energy Rated (UIS)
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Telecommunications
 - Server and Telecom Power Supplies
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Consumer and Computing
 - ATX Power Supplies
- Industrial
 - Welding
 - Battery Chargers
- Renewable Energy
 - Solar (PV Inverters)
- Switch Mode Power Supplies (SMPS)
- Applications using the Following Topologies
 - LCC
 - Phase shifted Bridge (ZVS)
 - 3-Level Inverter
 - AC/DC Bridge

| ORDERING INFORMATION | |
|---------------------------------|-----------------|
| Package | TO-220AB |
| Lead (Pb)-free and Halogen-free | SiHP24N65EF-GE3 |


| ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted) | | | |
|---|------------------|----------------|------|
| PARAMETER | SYMBOL | LIMIT | UNIT |
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Gate-Source Voltage AC ($f > 1$ Hz) | | 30 | |
| Continuous Drain Current ($T_J = 150$ °C) | V_{GS} at 10 V | $T_C = 25$ °C | A |
| | | $T_C = 100$ °C | |
| Pulsed Drain Current ^a | I_{DM} | 65 | |
| Linear Derating Factor | | 2 | W/°C |
| Single Pulse Avalanche Energy ^b | E_{AS} | 691 | mJ |
| Maximum Power Dissipation | P_D | 250 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to + 150 | °C |
| Drain-Source Voltage Slope | dV/dt | $T_J = 125$ °C | V/ns |
| Reverse Diode dV/dt^d | | 37 | |
| Soldering Recommendations (Peak Temperature) ^c | | 26 | |
| | for 10 s | 300 | °C |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DP} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 7$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.



| THERMAL RESISTANCE RATINGS | | | | |
|----------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 62 | °C/W |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 0.5 | |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | | |
|---|---------------------|---|--|------|------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | | 650 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$ | | - | 0.68 | - | V/°C |
| Gate-Source Threshold Voltage (N) | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | | 2 | - | 4 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20\text{ V}$ | | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}$ | | - | - | 1 | μA |
| | | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | | - | - | 500 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 12\text{ A}$ | - | 0.13 | 0.156 | Ω |
| Forward Transconductance | g_{fs} | $V_{DS} = 30\text{ V}, I_D = 12\text{ A}$ | | - | 7.2 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 100\text{ V}, f = 1\text{ MHz}$ | | - | 2656 | - | μF |
| Output Capacitance | C_{oss} | | | - | 119 | - | |
| Reverse Transfer Capacitance | C_{rss} | | | - | 4 | - | |
| Effective Output Capacitance, Energy Related ^a | $C_{o(er)}$ | $V_{DS} = 0\text{ V to } 520\text{ V}, V_{GS} = 0\text{ V}$ | | - | 96 | - | μF |
| Effective Output Capacitance, Time Related ^b | $C_{o(tr)}$ | | | - | 333 | - | |
| Total Gate Charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 12\text{ A}, V_{DS} = 520\text{ V}$ | - | 81 | 122 | nC |
| Gate-Source Charge | Q_{gs} | | | - | 17 | - | |
| Gate-Drain Charge | Q_{gd} | | | - | 36 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 520\text{ V}, I_D = 12\text{ A}, V_{GS} = 10\text{ V}, R_g = 9.1\text{ }\Omega$ | | - | 24 | 48 | ns |
| Rise Time | t_r | | | - | 34 | 68 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | - | 80 | 120 | |
| Fall Time | t_f | | | - | 46 | 92 | |
| Gate Input Resistance | R_g | $f = 1\text{ MHz}, \text{open drain}$ | | - | 0.72 | - | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 24 | A |
| Pulsed Diode Forward Current | I_{SM} | | | - | - | 65 | |
| Diode Forward Voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 12\text{ A}, V_{GS} = 0\text{ V}$ | | - | 0.9 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = I_S = 12\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}, V_R = 25\text{ V}$ | | - | 170 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | | - | 1.4 | - | μC |
| Reverse Recovery Current | I_{RRM} | | | - | 15 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

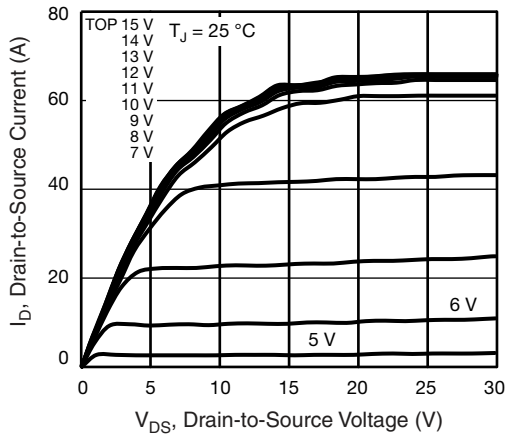


Fig. 1 - Typical Output Characteristics

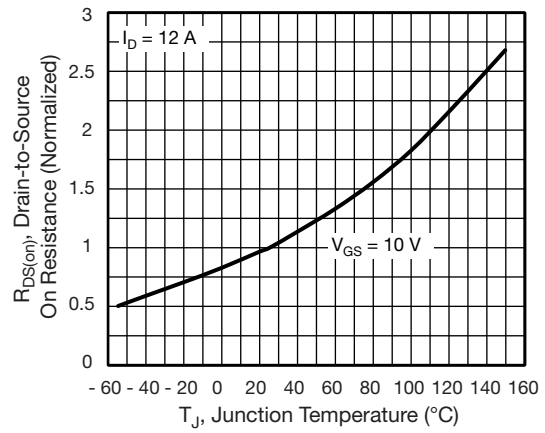


Fig. 4 - Normalized On-Resistance vs. Temperature

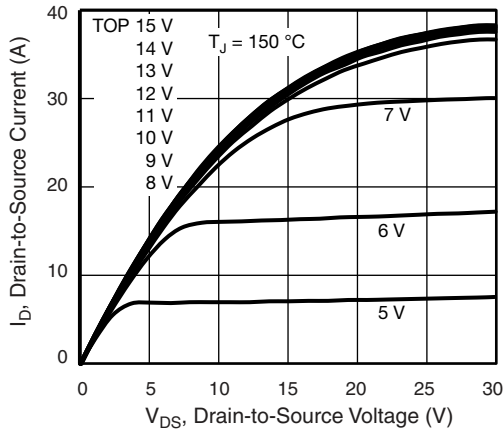


Fig. 2 - Typical Output Characteristics

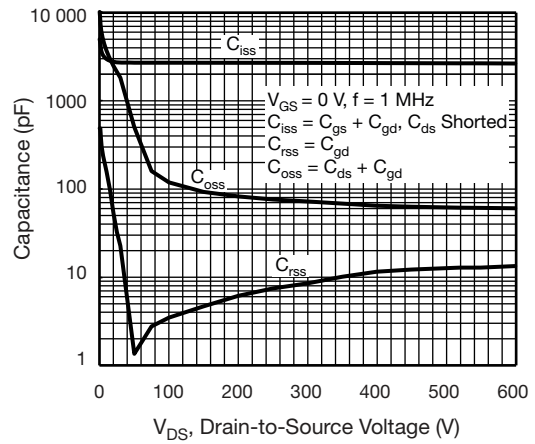


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

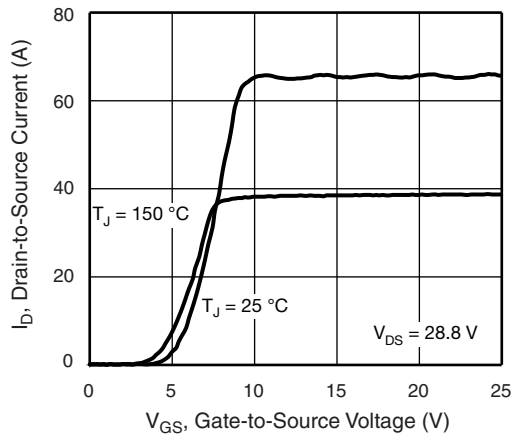


Fig. 3 - Typical Transfer Characteristics

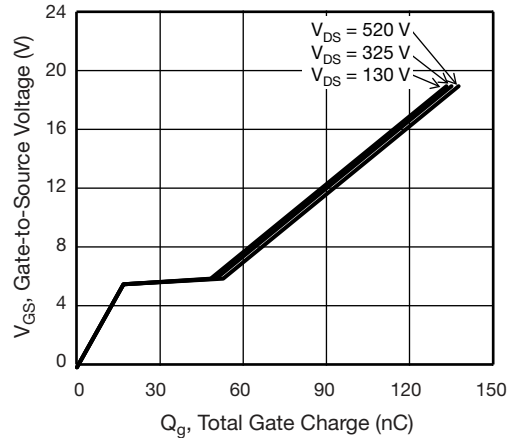


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

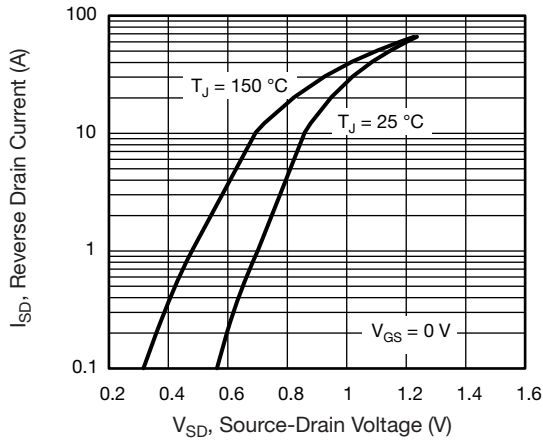


Fig. 7 - Typical Source-Drain Diode Forward Voltage

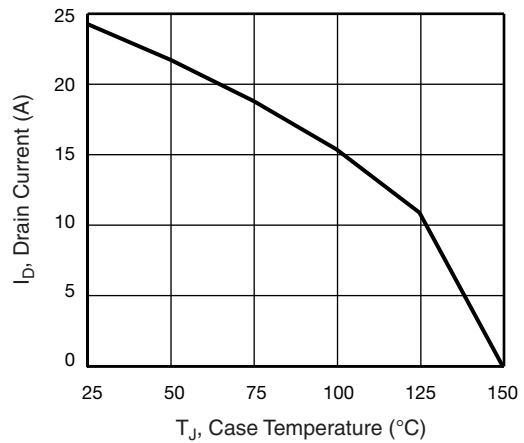


Fig. 9 - Maximum Drain Current vs. Case Temperature

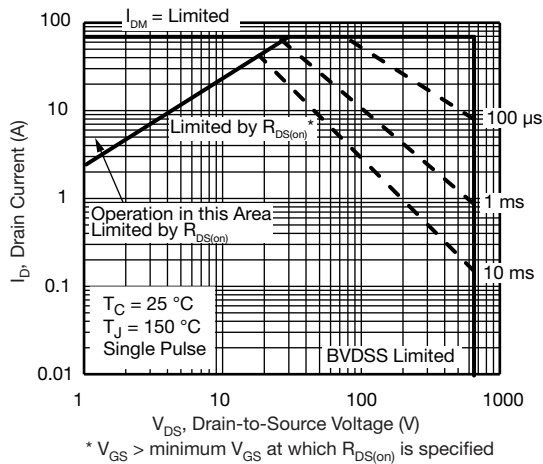


Fig. 8 - Maximum Safe Operating Area

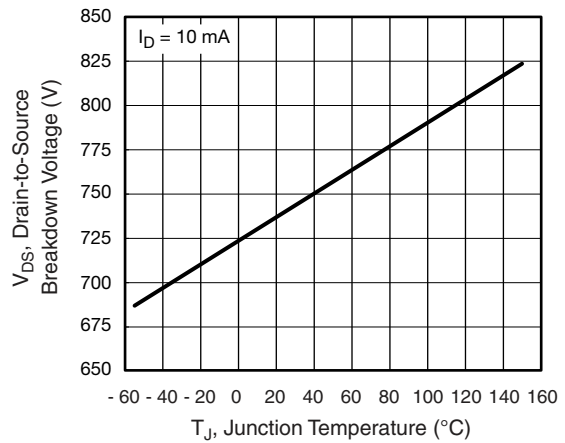


Fig. 10 - Temperature vs. Drain-to-Source Voltage

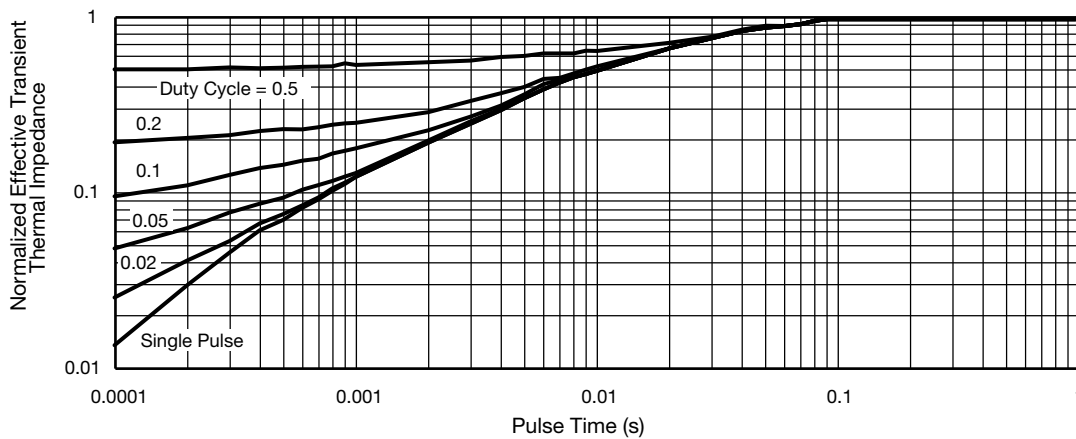


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

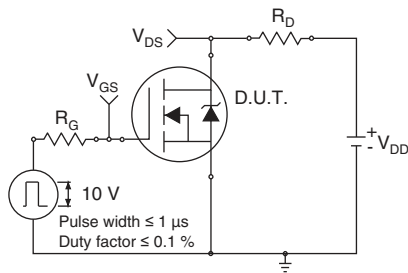


Fig. 12 - Switching Time Test Circuit

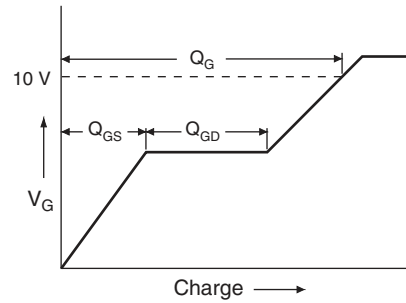


Fig. 16 - Basic Gate Charge Waveform

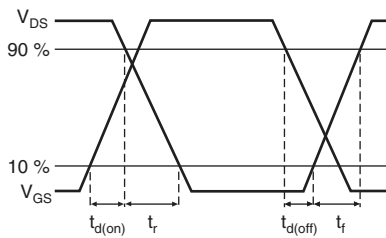


Fig. 13 - Switching Time Waveforms

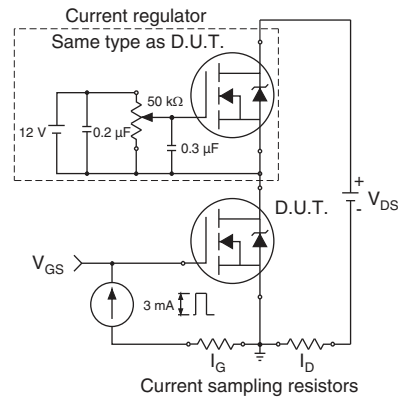


Fig. 17 - Gate Charge Test Circuit

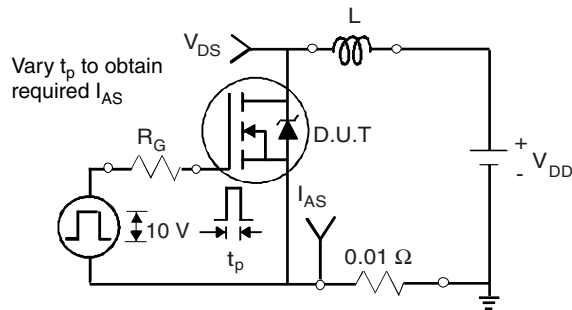


Fig. 14 - Unclamped Inductive Test Circuit

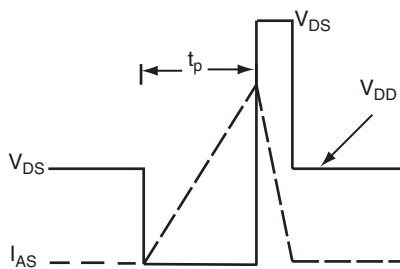
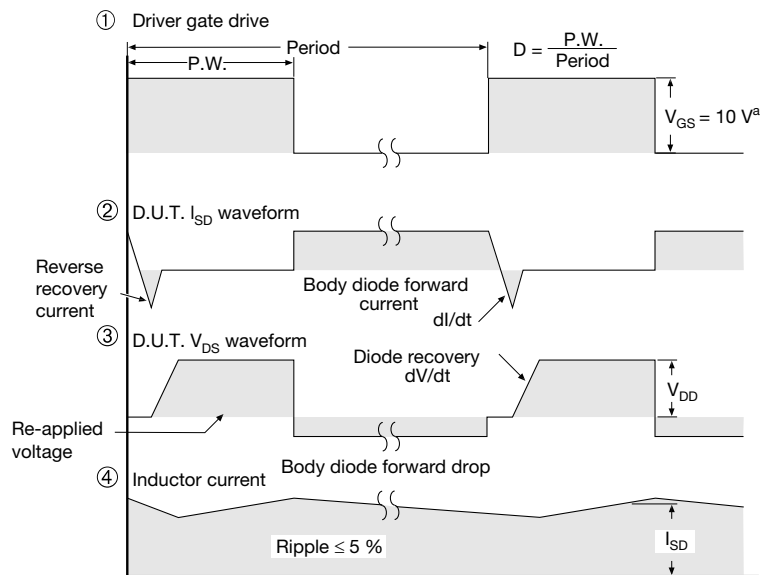
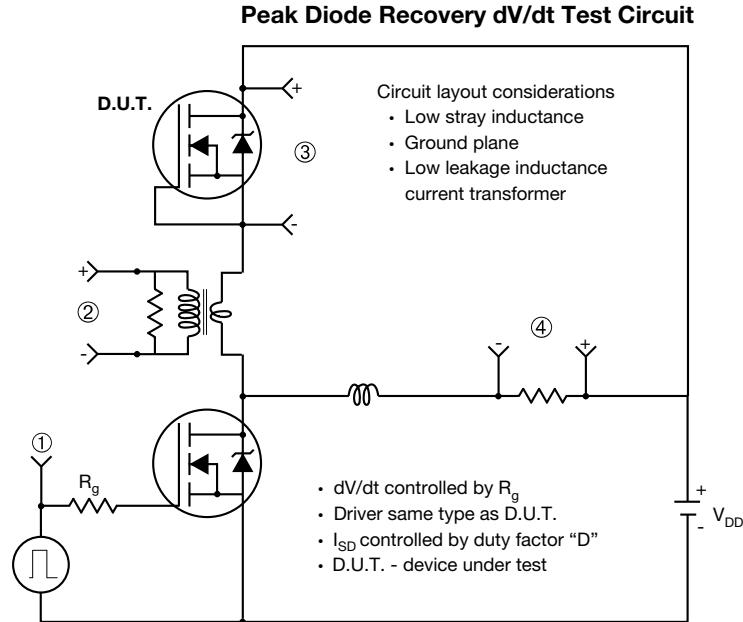


Fig. 15 - Unclamped Inductive Waveforms



Note

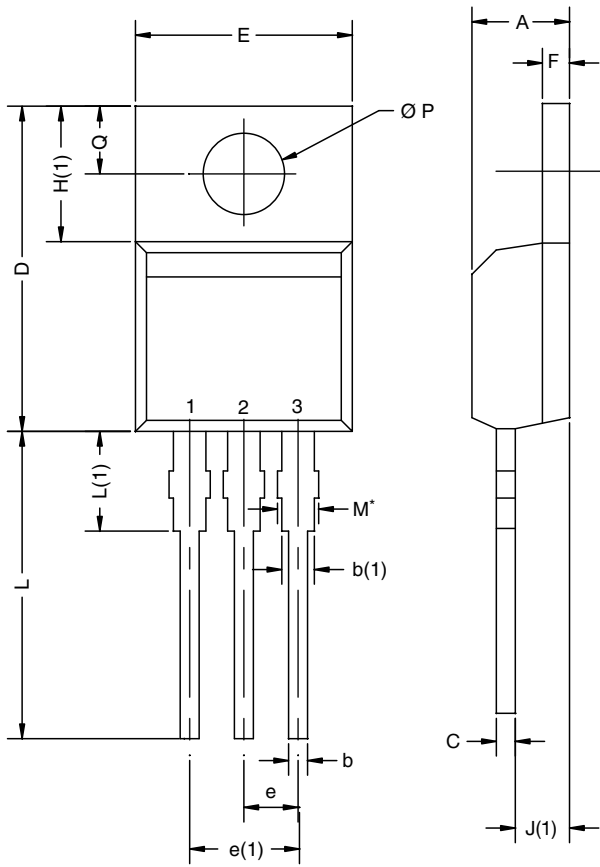
a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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TO-220AB

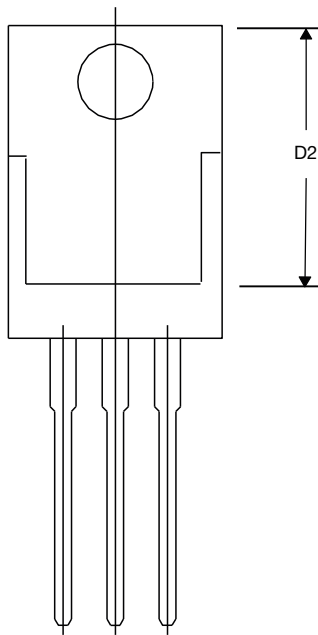


| DIM. | MILLIMETERS | | INCHES | |
|-----------------|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.25 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.01 | 0.027 | 0.040 |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.85 | 15.49 | 0.585 | 0.610 |
| D2 | 12.19 | 12.70 | 0.480 | 0.500 |
| E | 10.04 | 10.51 | 0.395 | 0.414 |
| e | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.35 | 14.02 | 0.526 | 0.552 |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 |
| $\varnothing P$ | 3.54 | 3.94 | 0.139 | 0.155 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |

ECN: T14-0413-Rev. P, 16-Jun-14
DWG: 5471

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM





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